视频编解码芯片规格书 ——AC5403 芯片

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版本: V1.0

日期: 2017.07.12

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AC5403 Features

Kernel architecture

- * 32KB I-Cache, 24KB D-Cache, Peripherals allowed to access the DDR through the cache
- **8** 64K on-chip SRAM
- ≈ 240MHz maximum operating frequency
- * 256 interrupt sources, 8-level programmable priority
- * Supports soft interrupt(virtual interrupt), priority can be configured

Video codec

- - 2304x1440@25fps/2304x1296<mark>@30fps(H.264)</mark>

2304x1440@25fps(H.264)+VGA(MJPEG)

1080P@30fps(H.264)+720P@30fps(H.264)

- ★ Support M-JPEG codec, maximum support 2304x1440@25fps, 4:2:0
- **☀** JPEG single resolution: 2560x1920

Video input and image processing

- ★ Maximum resolution: 2304x1440
- ★ Support RAW8/10/12 and YUV422 data format

- * Support image enhancement processing
- * Support image deinterlace
- * Support image scaling
- * Support Dual-way image input
- Support video realtime recording

Video output and graphics processing

- * Support DSI、DBI interface
- **※** Support CVBS output
- * Support image color enhancement
- * Support multi-layer image output
- ★ Supports image horizontal and vertical mirroring
- **★** Support image 90/180/270degree rotation
- * Maximum resolution 720P Vertical screen

Audio codec:

- * Support multi-channel multi-protocol audio voice codec though software
- Built-in coprocessor, support a variety of post-processing sound

Audio interface:

* Support 8KHz \ 16KHz \ 32KHz \ 44.1KHz \ 48KHz and other sampling frequency

Peripheral interface:

- * 41 programmable digital I/O pins
- * 4 32-bit reloadable timer, can be used as timing, capture, PWM
- * Hardware watchdog
- * 4 UART controller, of which 3 support with DMA cycle buffer
- ※ 3 SPI host controller, support DMA
- ★ 1 SPI FLASH interface
 - -Support standard dual quad modes
 - -Maximum support 16MB \ 80MHz
- * 1 USB 2.0 high speed, support DMA
- * 3 SDIO 2.0 interface, support DMA
- * LADC controller, support 4 channels, 16 data sources
- * DAC controller, support left and right channels, 16bit digital DAC
- * RTC, support alarm clock and time base, support wake up chip
- * IIC controller, support master mode and slave mode
- * EMI controller, support DMA transmit
- * AES128 and SHA1 ENCRYPT/DECRYPT
- Built-in AVOUT

Analog peripheral features:

- ※ 3 clock oscillation circuit
- * HTC (High precision on-chip oscillator)
- ※ High speed USB 2.0 PHY
- * 5 clock generators(PLL), provide a variety of different frequencies of the system
- ★ 16-bit stereo audio DAC, SNR > 88 dB
- ★ 4-channel stereo ADC with 1-channel MIC amplifier, SNR > 72 dB
- * 1-channel 8-level low voltage detector
- * 3LDO: 3.3V-1.2V, 3.3V-1.8V/2.5V, 3.3V-2.8V
- ★ 2Line 1Gbps/lane DSI phy
- * 2Line 1Gbps/lane CSI phy

External memory interface:

- * DDRX controller, support DDR1/DDR2、16bit data bit-wide, DDR1 fastest support 250MHz, DDR2 fastest support 400MHz
 - -Maximum support 64MB

Supply Voltage:

符号	参数	最小	典型	最大	单位
VDDIO	IO Power	3.0	3.3	3.6	V
SVDD1/2/3	IO Power	3.0	3.3 1.8	3.6	V
DRVDD	DDR2 Power	1.7	1.8	1.9	V
DRVDD	DDR1 Power	2.3	2.5	2.7	V
VDD	Core Power	1.08	1.2	1.32	V

注: SVDD1 为 IO (PB5-PB10、PB14、PB15) 的电源; SVDD2 为 IO (PA11-PA14、PB0、PB1、PE0、PE1) 的电源; SVDD3 为 IO (PG2、PG8-PG15) 的电源.

- ※ 工作温度 (-40℃ 至 +85℃)
- * 存储温度 (-65℃ 至 +150℃)

Package:

☆ QFN88 (10mm X 10mm)



一、引脚定义

1.1 引脚分配

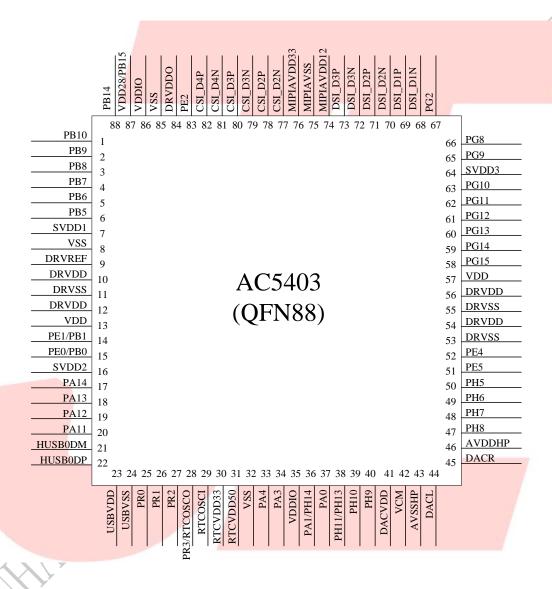


图 1-1 AC5403 _QFN88 引脚分配图

1.2 引脚描述

表 1-1 AC5403 _QFN88 引脚描述

Pin#	Name	I/O Type	Function	Other Function
1	PB10	1/0	GPI0	SPI2_DAT3B(3): SPI2 Data3 (B) SD1_DAT1C: SD1 Data1 (C)
2	PB9	1/0	GPI0	SPI2_CLKB: SPI2 Clock (B) SD1_DATOC: SD1 Data0 (C)
3	PB8	1/0	GPI0	SPI2_DOB(0): SPI2 Data Out (B) SD1_CLKC: SD1 Clock (C)
4	PB7	1/0	GPI0	SPI2_DAT2B(2): SPI2 Data2 (B) SD1_CMDC: SD1 CMD (C)
5	PB6	1/0	GPI0	SPI2_DIB(1): SPI2 Data In (B) SD1_DAT3C: SD1 Data3 (C)
6	PB5	1/0	GPI0	SPI2_CSB: SPI2 Chip Select(B) SD1_DAT2C: SD1 Data2 (C)
7	SVDD1	Р	IO Power1	
8	VSS	Р	Digital Ground	
9	DRVREF	Р	DDR REF	
10	DRVDD	Р	DDR Power	
11	DRVSS	Р	DDR Ground	
12	DRVDD	Р	DDR Power	
13	VDD	Р	Core Power	
1.4	PB1	1/0	GPI0	IIC_SDA1_A: IIC1 SDA (A)
14	PE1	1/0	GPI0	SDO_DAT1D: SDO Data1 (D) UART3_RXA: Uart3 Data In (A)
15	PB0	1/0	GPI0	IIC_SCL1_A: IIC1 SCL (A)
	PE0	1/0	GPI0	SDO_DATOD: SDO DataO (D) UART3_TXA: Uart3 Data Out (A)
16	SVDD2	Р	IO Power2	
17	PA14	1/0	GPI0	ALNK_WSB: Audio Link WS (B) SDO_CLKD: SDO Clock (D)
18	PA13	1/0	GPI0	ALNK_CKB: Audio Link Clock (B) SDO_CMDD: SDO CMD (D)

	T	ı		
19	PA12	1/0	GPI0	ALNK_D3B: Audio Link Data3 (B) SDO_DAT2D: SDO Data2 (D)
20	PA11	I/0	GPI0	ALNK_D2B: Audio Link Data2 (B) SDO_DAT3D: SDO Data3 (D)
21	HUSB0DM	I/0	HUSB0DM	
22	HUSB0DP	I/0	HUSB0DP	
23	USBVDD	Р	USB Power	^ `
24	USBVSS	Р	USB Ground	——
25	PR0	1/0	RTC IO	PINR: PIN Reset
26	PR1	1/0	RTC IO	PINR: PIN Reset ADC13: ADC Input Channel 13
27	PR2	1/0	RTC IO	PINR: PIN Reset(Default) ADC12: ADC Input Channel 12
28	PR3	I/0	RTC IO	PINR: PIN Reset
40	RTCOSCO	I/0	RTC OSCO	
29	RTCOSCI	I/0	RTC OSCI	
30	RTCVDD33	Р	RTC Power	
31	RTCVDD50	Р	RTC Power	
32	VSS	Р	Digital Ground	
33	PA4	1/0	GPI0	SPIO_CLKA: SPIO Clock (A) SFC_CLK: SFC Clock
34	PA3	1/0	GPI0	SPIO_DOA(0): SPIO Data Out (A) SFC_DO(0): SFC Data Out
35	VDDIO	Р	IO Power	
	PA1	1/0	GPI0	IIC_SDA1_B: IIC1 SDA (B) SPI0_DIA(1): SPI0 Data In (A) SFC_DI(1): SFC Data In
36	PH14	1/0	GPI0	UART1_TXC: Uart1 Data Out (C) ADC10: ADC Channel 10 CLKOUT1: Clock Out1 IIC_SDAO_B: IICO SDA (B) Wakeup14: Port Wakeup 14 SPI1_DOC(0): SPI1 Data Out (C)
37	PA0	1/0	GPI0	SPIO_CSA: SPIO Chip Select (A) SFC_CS: SFC Chip Select

	1	•	1	
38	РН13	I/0	GPI0	UARTO_RXC: UartO Data In (C) AVOUT: AV Output TMR3: Timer3 Clock In SPI1_DIC(1): SPI1 Data In (C)
	PH11	1/0	GPI0	MICR: MIC Right Channel SD1_DATOA: SD1 DataO (A)
39	РН10	1/0	GPI0	AMUX1R: Simulator Channel 1 Right SD1_CLKA: SD1 Clock (A) Wakeup13: Port Wakeup 13 UART2_TXB: Uart2 Data Out (B)
40	РН9	I/0	GPI0	AMUX1L: Simulator Channel 1 Left SD1_CMDA: SD1 CMD (A) UART2_RXB: Uart2 Data In (B)
41	DACVDD	Р	DAC Power	
42	VCM	Р	VCM	
43	AVSSHP	Р	Head Phone Ground	
44	DACL	0	DAC Left Channel	DACL
45	DACR	0	DAC Right Channel	DACR
46	AVDDHP	Р	Head Phone Power	
47	PH8	I/0	GPI0	AMUXOR: Simulator Channel O Right SD1_DAT3A: SD1 Data3 (A)
48	PH7	I/0	GPI0	AMUXOL: Simulator Channel O Left SD1_DAT2A: SD1 Data2 (A) Wakeup12: Port Wakeup 12
49	РН6	I/0	GPI0	MICL:MIC Left Channel
50	PH5	I/0	GPI0	UART1_RXB: Uart1 Data In (B) SD1_DAT1A: SD1 Data1 (A)
51	PE5	I/0	GPI0	ADC8: ADC Channel 8 IIC_SDA1_D: IIC1 SDA (D) SPI1_DOA(0): SPI1 Data Out (A) Wakeup11: Port Wakeup 11

52	PE4	I/0	GPI0	IIC_SCL1_D: IIC1 SCL (D) SPI1_CLKA: SPI1 Clock (A) Wakeup10: Port Wakeup 10
53	DRVSS	Р	DDR Ground	
54	DRVDD	Р	DDR Power	
55	DRVSS	Р	DDR Ground	
56	DRVDD	Р	DDR Power	
57	VDD	Р	Core Power	
58	PG15	1/0	GPI0	LCD_DAT15A: LCD Data15 (A) EMI_D15A: EMI Data15 (A)
59	PG14	1/0	GPI0	LCD_DAT14A: LCD Data14 (A) EMI_D14A: EMI Data14 (A)
60	PG13	I/0	GPI0	LCD_DAT13A: LCD Data13 (A) EMI_D13A: EMI Data13 (A) MC PWM_H3_A SD2_DAT1B: SD2 Data1 (B)
61	PG12	1/0	GPI0	LCD_DAT12A: LCD Data12 (A) EMI_D12A: EMI Data12 (A) MC PWM_L3_A SD2_DAT0B: SD2 Data0 (B)
62	PG11	1/0	GPI0	LCD_DAT11A: LCD Data11 (A) EMI_D11A: EMI Data11 (A) MC PWM_H2_A SD2_CLKB: SD2 Clock (B)
63	PG10	1/0	GPI0	LCD_DAT10A: LCD Data10 (A) EMI_D10A: EMI Data10 (A) MC PWM_L2_A SD2_CMDA: SD2 CMD (A)
64	SVDD3	Р	IO Power3	
65	PG9	I/0	GPI0	LCD_DAT9A: LCD Data9 (A) EMI_D9A: EMI Data9 (A) MC PWM_H1_A SD2_DAT3B: SD2 Data3 (B)
66	PG8	I/0	GPI0	LCD_DAT8A: LCD Data8 (A) EMI_D8A: EMI Data8 (A) MC PWM_L1_A SD2_DAT2B: SD2 Data2 (B)
67	PG2	I/0	GPI0	LCD_DENAB: LCD Data Enable EMI_WRAB: EMI Write

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			MIPI DSI	MIPI DSI data (0/1) lane (p/n)
68	DSI_D1N	0	lane	MIPI DSI clock lane (p/n)
			MIPI DSI	MIPI DSI data (0/1) lane (p/n)
69	DSI_D1P	0	lane	MIPI DSI clock lane (p/n)
	DOT DOM		MIPI DSI	MIPI DSI data (0/1) lane (p/n)
70	DSI_D2N	0	lane	MIPI DSI clock lane (p/n)
7.1	DCT DOD	0	MIPI DSI	MIPI DSI data (0/1) lane (p/n)
71	DSI_D2P	0	lane	MIPI DSI clock lane (p/n)
72	DCT D2M	0	MIPI DSI	MIPI DSI data (0/1) lane (p/n)
12	DSI_D3N	U	1ane	MIPI DSI clock lane (p/n)
73	DSI_D3P	0	MIPI DSI	MIPI DSI data (0/1) lane (p/n)
13	D31_D3F	U	1ane	MIPI DSI c <mark>lock lane (p/n)</mark>
74	MIPIAVDD12	Р	MIPI AVDD	
75	MIPIAVSS	Р	MIPI AVSS	
76	MIPIAVDD33	Р	MIPI Power	
77	CSI_D2N	I	MIPI CSI	
11	CS1_DZN	1	1ane	MIPI CSI clock lane (p/n)
78	CSI_D2P	I	MIPI CSI	
10	C31_D21	1	lane	MIPI CSI clock lane (p/n)
79	CSI_D3N	I	MIPI CSI	
13	C31_D3N	1	1ane	MI <mark>PI CSI data (0</mark> /1) lane (p/n)
80	CSI D3P	I	MIPI CSI	A Total Tota
	651_561	- 1	lane	MIPI CSI data (0/1) lane (p/n)
81	CSI_D4N	I	MIPI CSI	
			lane	MIPI CSI data (0/1) lane (p/n)
82	CSI D4P	I	MIPI CSI	
			lane	MIPI CSI data (0/1) lane (p/n)
0.0	DEG	T /0	ODTO	VPP
83	PE2	I/0	GPI0	CLKOUTO: Clock OutO IIC_SCL1_C: IIC1 SCL (C)
			DDR Power	IIC_SCLI_C: IICI SCL (C)
84	DRVDDO	P	Output	
	, , , , , , , , , , , , , , , , , , ,		Digital	
85	VSS	Р	Ground	
7			or ourid	
86	VDDIO	Р	IO Power	
	VDD28	Р	AVDD28	
87		-		
	PB15	I/0	GPI0	UARTO_RXD: UartO Data In (D)
				OSC02

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88	PB14	1/0	GPI0	UARTO_TXD: UartO Data Out (D) OSCI2 TMRO: TimerO Clock In ADC4: ADC Channel 4 Wakeup9: Port Wakeup 9
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(★说明: 1、P----Power Supply 2、I----Input 3、O----Output 4、I/O----Bi-direction)

二、电气特性

2.1 IO 输入、输出高低逻辑特性

表 2-1

	输入特性								
符号	参数	最小	典型	最大	单位	测试条件			
V _{IL}	Low-Level Input Voltage	-0.3	-	0.3* VDDIO	V	VDDIO = 3.3V			
V_{IH}	High-Level Input Voltage	0.7* VDDIO	-	VDDIO+0.3	V	VDDIO = 3.3V			
	输出特性								
V_{OL}	Low-Level Output Voltage	-	-	0.1* VDDIO	V	VDDIO = 3.3V			
V_{OH}	High-Level Output Voltage	0.9* VDDIO	-	-	V	VDDIO = 3.3V			

2.2 IO 输出能力、上<mark>下拉电阻特</mark>性

表 2-2

Port □	输出能力	上拉电阻	下拉电阻	备注
PAO、PA1				
PA3、PA4				
PA11 - PA14		7		
PB0、PB1				
PB5 - PB10				1
PB14、PB15	强驱: 24mA	10K	60K	
PE0、PE1	弱驱: 8mA	1010	OOK	3
PE4、PE5				
PG2				
PG8 - PG15				
PH5 - PH11				
PH13、PH14				
PE2	8mA(无强弱驱之分)	10K	10K	
PR0-PR3	8mA(片内串接 200Ω电阻)	10K	60K	RTC 模块需供电

(★说明:上下拉电阻的精度约为±20%)

2.3 DAC 特性

表 2-3

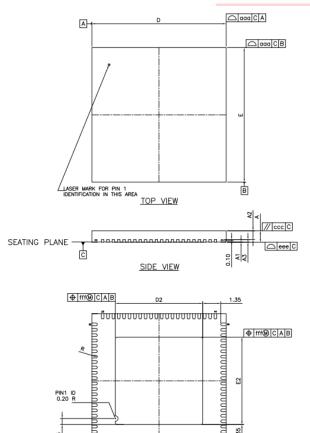
符号	参数	最小	典型	最大	单位	测试条件
SNR	Signal to Noise Ratio		94		dB	1KHz,SR=44.1KHz,静音文件, DACVDD with 1u cap
THD+N	Total Harmonic Distortion+ Noise		-75		dB	1KHz,SR=44.1KHz, DACVDD with 1u cap



三、封装

3.1 QFN_88PIN 封装图

图 3-1 AC5403_QFN88 封装图



ADDOMESTICATION OF THE PROPERTY OF THE PROPERT

BOTTOM VIEW

ltem	Symbol	MIN.	NOM.	MAX.	
total height	А	0.80	0.85	0.90	
stand off		A1	0.00	0.02	0.05
mold thickness		A2	0.60	0.65	0.70
leadframe thickness		A3		0.20 REF.	
lead width		b	0.15	0.20	0.25
	Х	D	9.90	10.00	10.10
package size	Υ	E	9.90	10.00	10.10
E-PAD size	Х	D2	6.40	6.50	6.60
E-PAD SIZE	Υ	E2	6.40	6.50	6.60
lead length		L	0.30	0.40	0.50
lead pitch		е	0.40 bsc		
lead arc		R	0.075		
Package profile of a sur	face	aaa	0.10		
Lead position	bbb	0.07			
Parallelism	ccc	0.10			
Lead position	ddd	0.05			
Lead profile of a surface	eee	0.08			
Epad position		fff		0.10	

四、版本信息

日期	版本号	描述	
2017.07.12	V1.0	原始版本。	
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			1

